


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/23/14399
1.3 Title of PCN	Introduction of plasma dicing for CMOSF8H+ industrial grade EEPROM
1.4 Product Category	M24C02-WMN6TP M24C02-RMN6TP M24C02-FMN6TP M24C04-WMN6TP M24C04-RMN6TP M24C04-FMN6TP
1.5 Issue date	2023-11-17

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marie-France FLORENTIN
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	ST Shenzhen (China)

4. Description of change

	Old	New
4.1 Description	The CMOSF8H+ process technology running in ST Rousset (France) 8 inches fab (R8) benefits of introduction of plasma dicing technology before assembly of SO8N.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	- Form: no change - Fit: no change - Function: no change	

5. Reason / motivation for change

5.1 Motivation	Plasma dicing allows capacity improvement and better die singulation quality. All the M24C04, M24C02 industrial grade EEPROM currently produced with CMOSF8H+ process technology will benefit from this change.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	N/A
-----------------	-----

7. Timing / schedule

7.1 Date of qualification results	2023-11-15
7.2 Intended start of delivery	2024-02-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

14399 Public product.pdf
14399 PCN PLASMA DICING CMOSF8H+.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24C02-RMN6TP	
	M24C02-WMN6TP	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved